

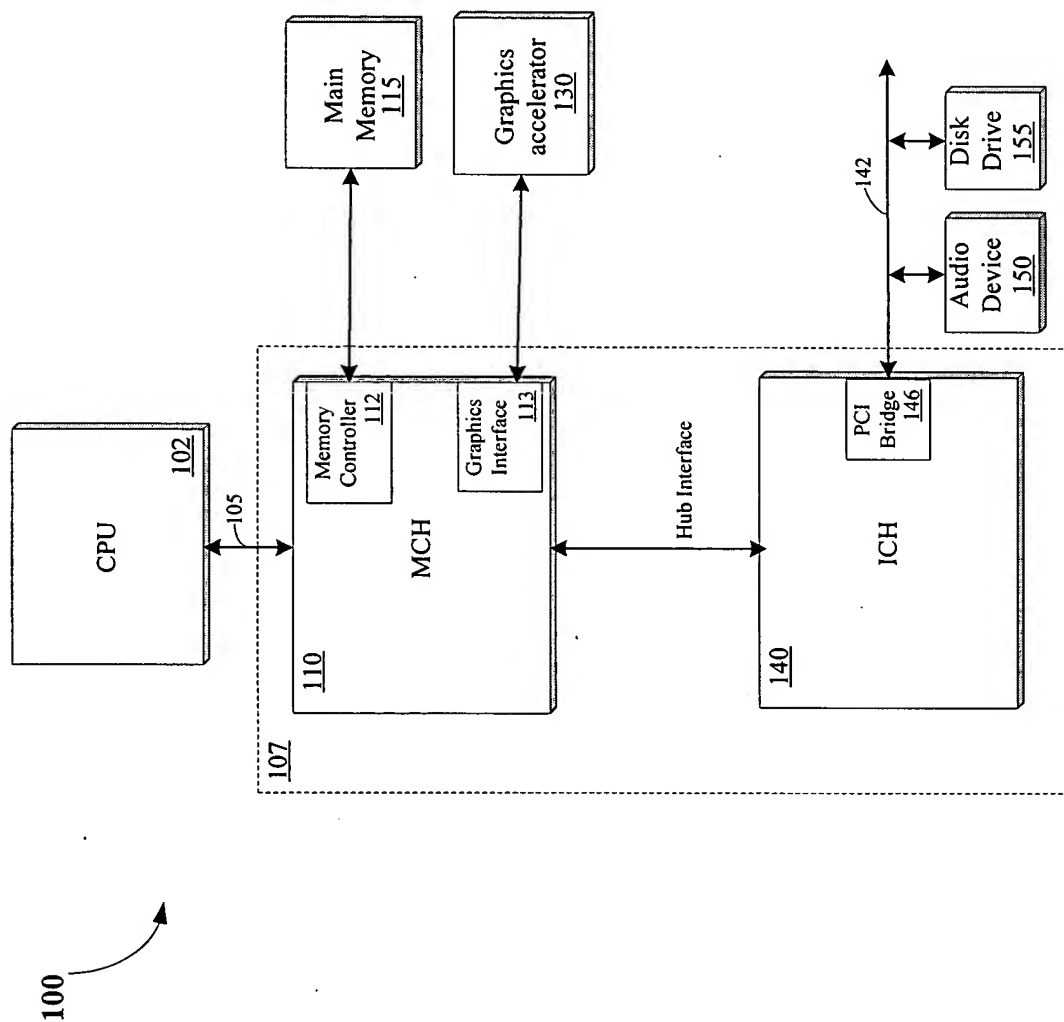
"THERMAL SOLUTION FOR ELECTRONICS COOLING USING
A HEAT PIPE IN COMBINATION WITH ACTIVE LOOP SOLUTION"

by Eric DiStefano, Himanshu Pokhama

Docket No. P18069 Contact: David N. Tran Reg. No. 50,804 Phone No. 408-765-4692

Sheet 1 of 6

FIG. 1



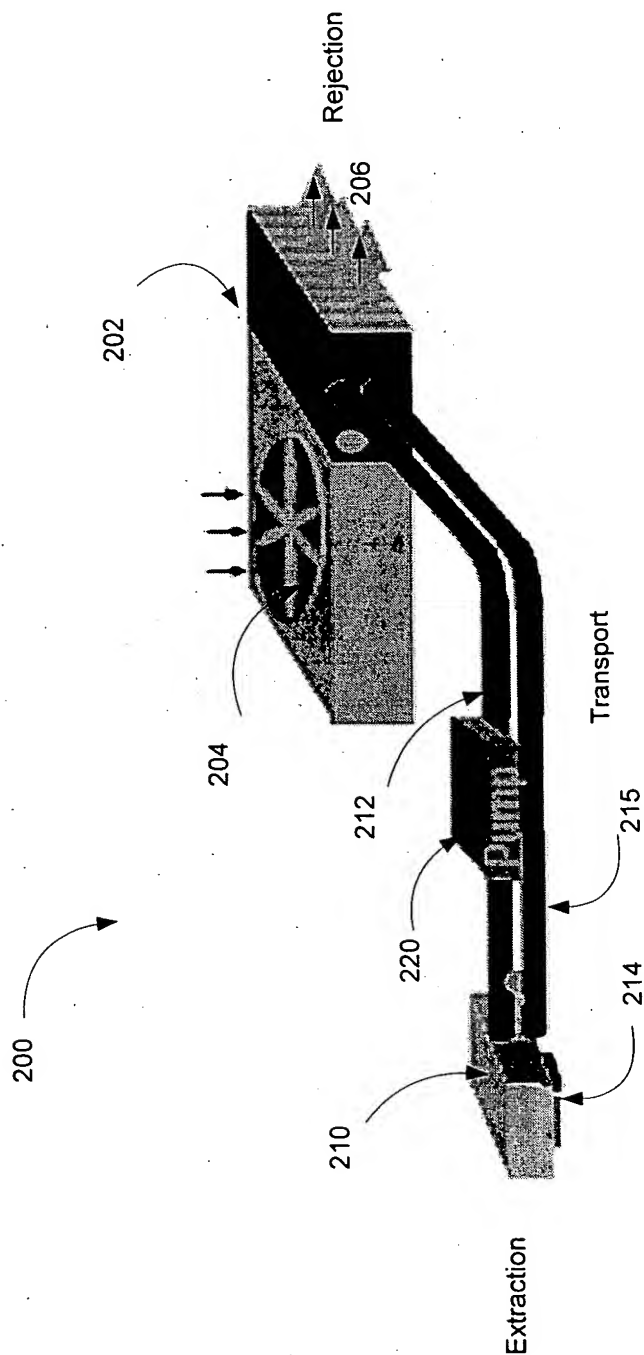


FIG. 2

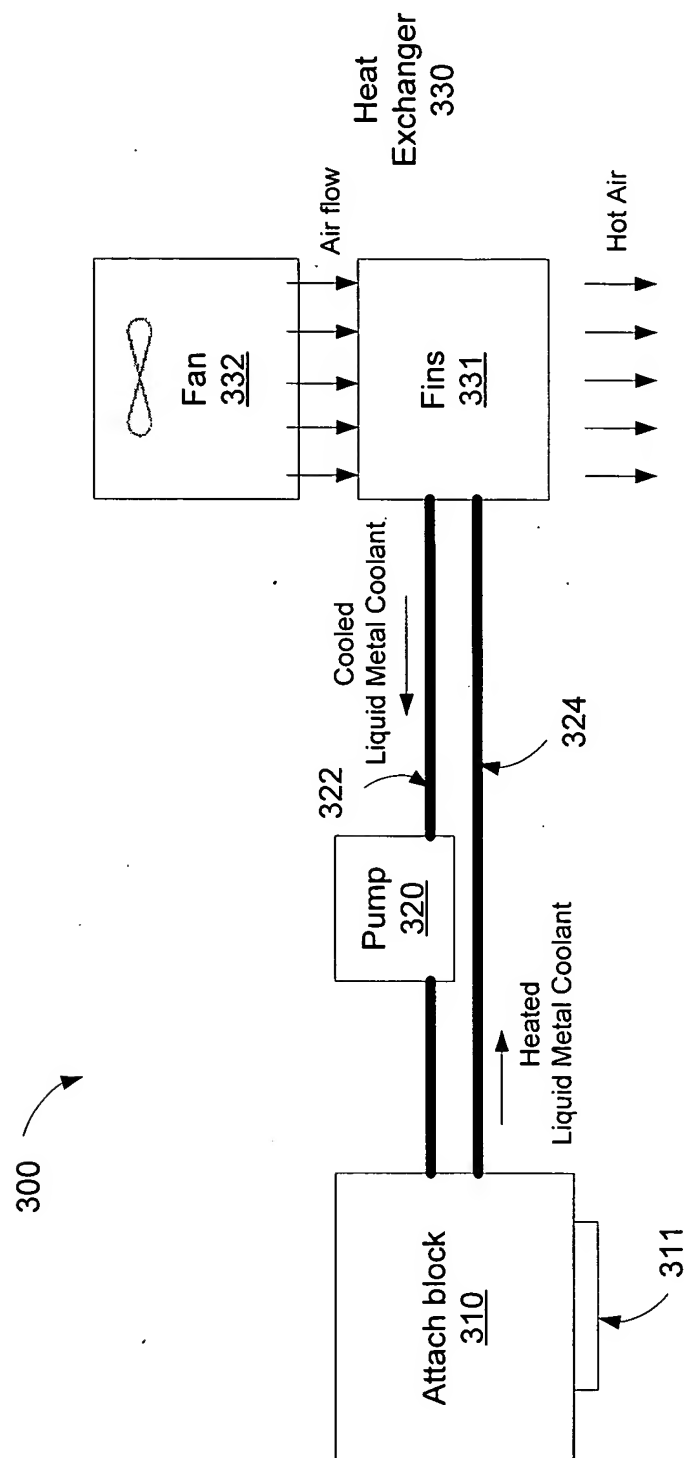


FIG. 3

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Sheet 4 of 6

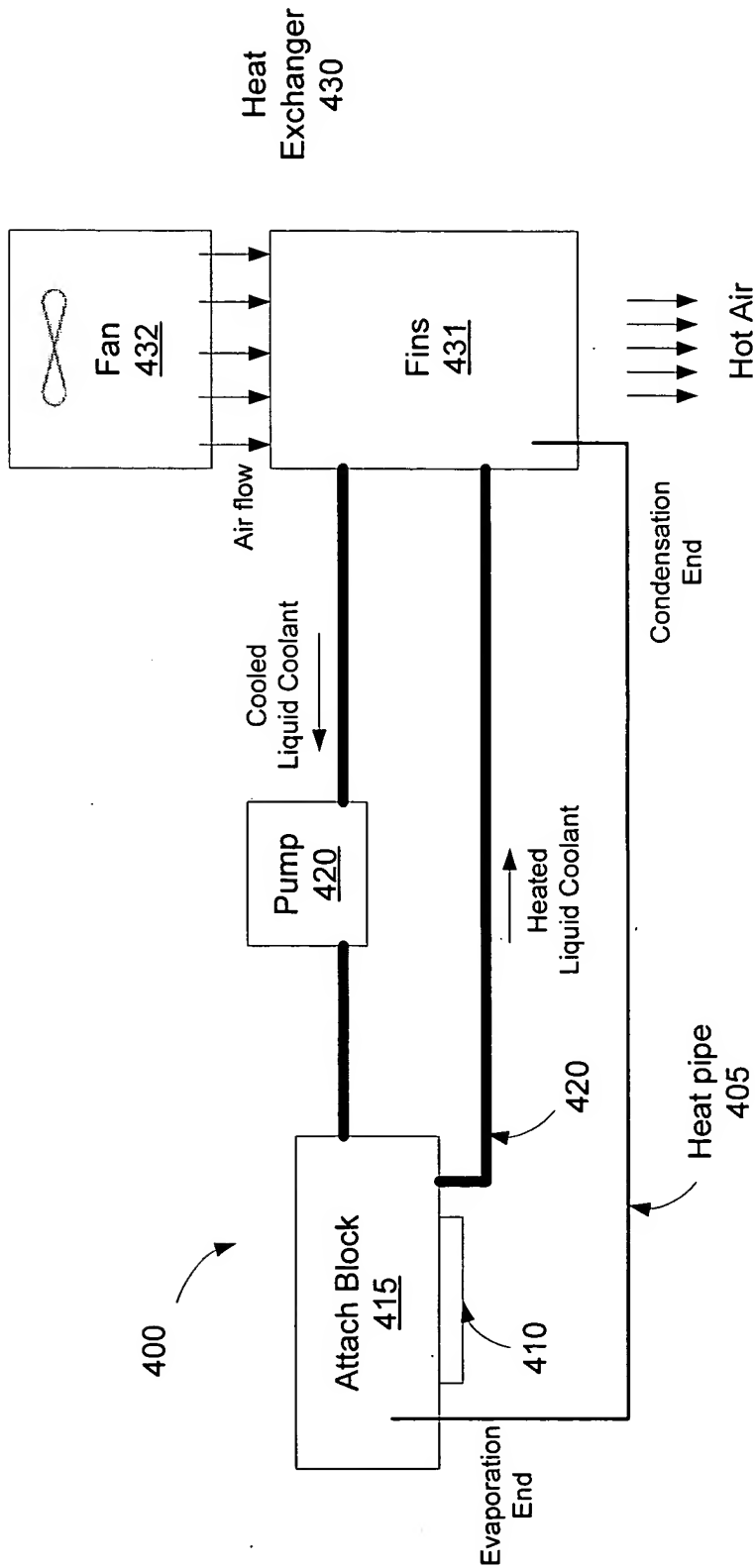
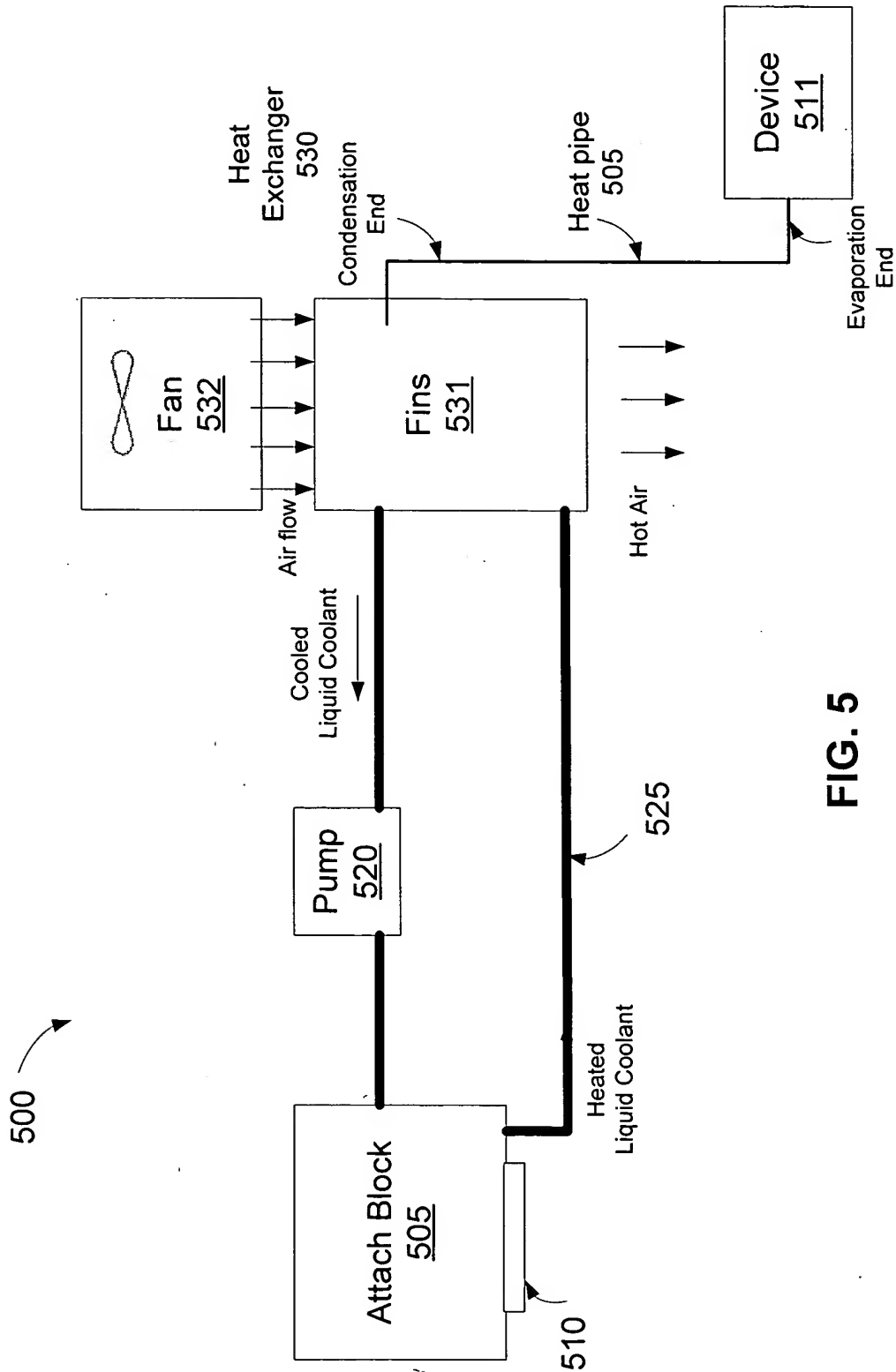


FIG. 4

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Sheet 5 of 6



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Sheet 6 of 6

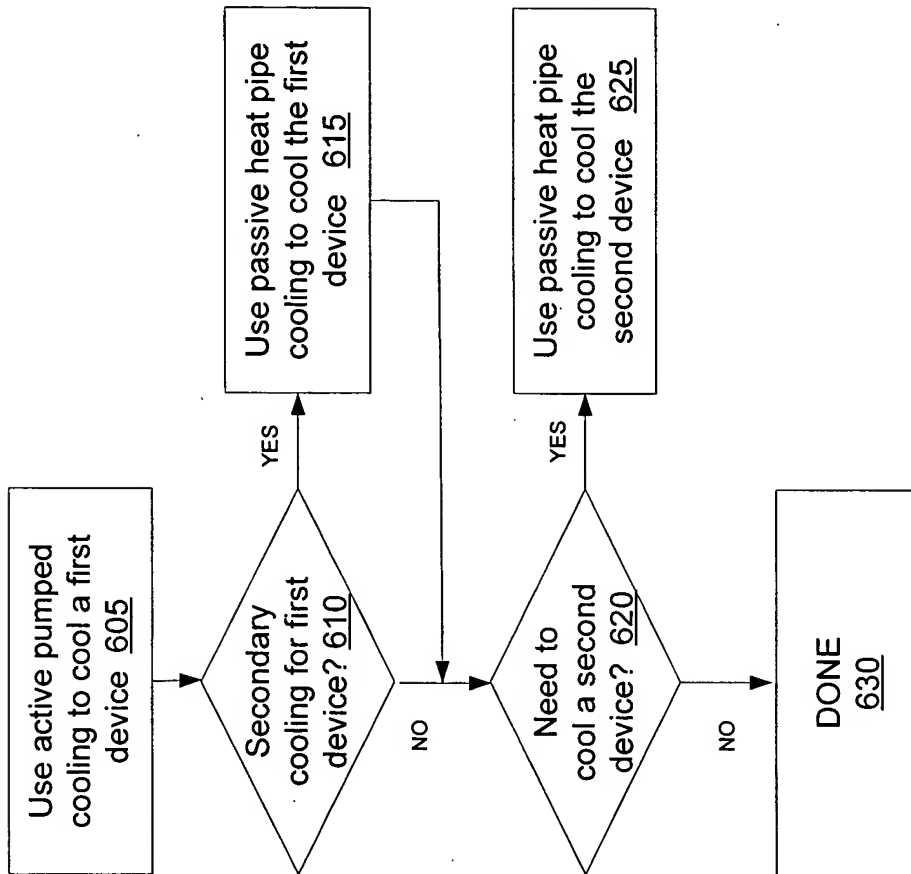


FIG. 6